# **Surface Mount Ultrafast Power Rectifiers**

Ideally suited for high voltage, high frequency rectification, or as free wheeling and protection diodes in surface mount applications where compact size and weight are critical to the system.

### **Features**

- Small Compact Surface Mountable Package with J-Bend Leads
- Rectangular Package for Automated Handling
- High Temperature Glass Passivated Junction
- Low Forward Voltage Drop (0.95 Volts Max @ 2.0 A, T<sub>J</sub> = 150°C)
- Pb-Free Packages are Available

#### **Mechanical Characteristics:**

- Case: Epoxy, Molded
- Weight: 95 mg (Approximately)
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead and Mounting Surface Temperature for Soldering Purposes: 260°C Max. for 10 Seconds
- Polarity: Polarity Band Indicates Cathode Lead

### **MAXIMUM RATINGS**

Rating	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage MURS230T3 MURS240T3	V <sub>RRM</sub> V <sub>RWM</sub> V <sub>R</sub>	300 400	V
Average Rectified Forward Current @ T <sub>L</sub> = 150°C @ T <sub>L</sub> = 125°C	I <sub>F(AV)</sub>	1.0 2.0	Α
Non-Repetitive Peak Surge Current (Surge applied at rated load conditions halfwave, single phase, 60 Hz)	I <sub>FSM</sub>	35	Α
Operating Junction Temperature Range	TJ	-65 to +175	°C

## THERMAL CHARACTERISTICS

Rating	Symbol	Max	Unit
Thermal Resistance, Junction–to–Lead (T <sub>L</sub> = 25°C)	$R_{ heta JL}$	13	°C/W

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.



## ON Semiconductor®

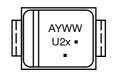
http://onsemi.com

## **ULTRAFAST RECTIFIERS** 2 AMPERES, 300-400 VOLTS



**SMB** CASE 403A

#### MARKING DIAGRAM



= Assembly Location

= Year = Work Week WW U2x = Device Code

> x=F for MURS230T3 = G for MURS240T3

= Pb-Free Package

(Note: Microdot may be in either location)

## **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>
MURS230T3	SMB	2500 Tape & Reel
MURS230T3G	SMB (Pb-Free)	2500 Tape & Reel
MURS240T3	SMB	2500 Tape & Reel
MURS240T3G	SMB (Pb-Free)	2500 Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

## **ELECTRICAL CHARACTERISTICS**

Characteristic		Value	Unit
Maximum Instantaneous Forward Voltage (Note 1) $ \begin{aligned} &(i_F=2.0 \text{ A, } T_J=25^{\circ}\text{C}) \\ &(i_F=2.0 \text{ A, } T_J=150^{\circ}\text{C}) \end{aligned} $	V <sub>F</sub>	1.30 1.05	V
Maximum Instantaneous Reverse Current (Note 1) (Rated DC Voltage, T <sub>J</sub> = 25°C) (Rated DC Voltage, T <sub>J</sub> = 150°C)	İR	5.0 150	μΑ
Maximum Reverse Recovery Time $ \begin{aligned} &(i_F=1.0 \text{ A, di/dt}=50 \text{ A/}\mu\text{s}) \\ &(i_F=0.5 \text{ A, }i_R=1.0 \text{ A, }I_R \text{ to } 0.25 \text{ A}) \end{aligned} $	t <sub>rr</sub>	65 50	ns
Maximum Forward Recovery Time (i <sub>F</sub> = 1.0 A, di/dt = 100 A/μs, Rec. to 1.0 V)	t <sub>fr</sub>	50	ns

<sup>1.</sup> Pulse Test: Pulse Width = 300  $\mu$ s, Duty Cycle  $\leq$  2.0%.

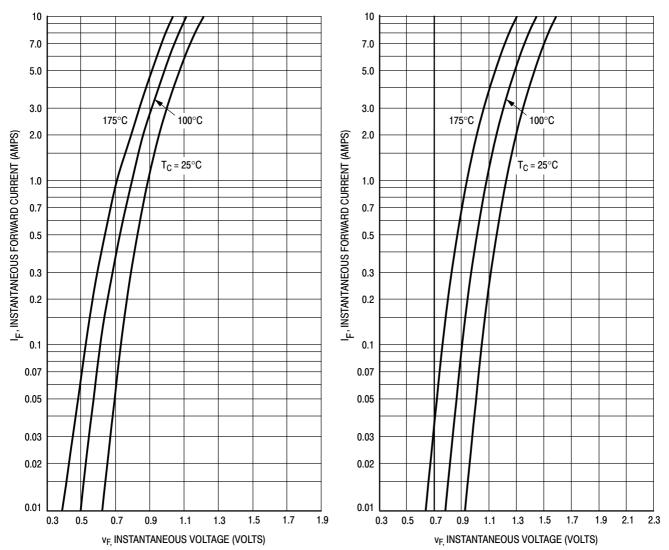
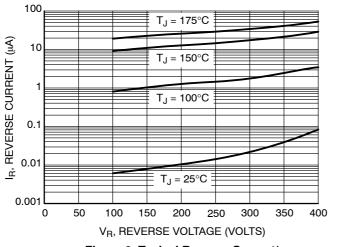
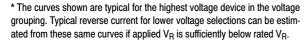


Figure 1. Typical Forward Voltage

Figure 2. Maximum Forward Voltage







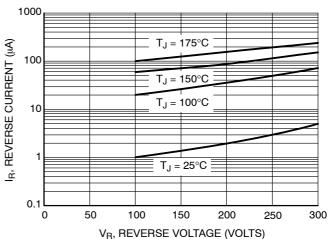


Figure 4. Maximum Reverse Current for MURS230T3

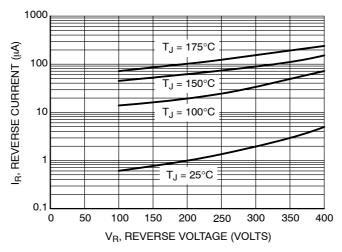


Figure 5. Maximum Reverse Current for MURS240T3

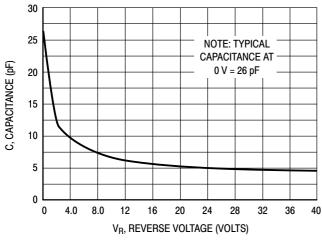


Figure 6. Typical Capacitance

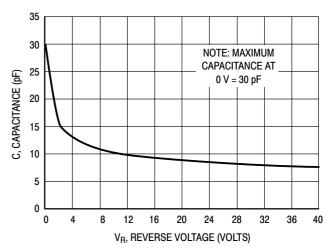


Figure 7. Maximum Capacitance

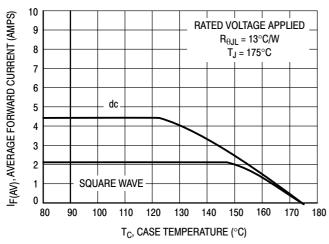


Figure 8. Current Derating, Case

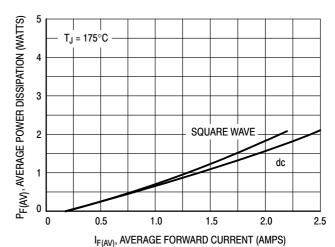
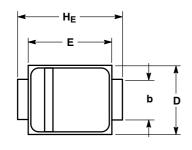
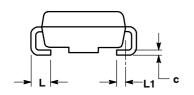


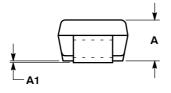
Figure 9. Power Dissipation

### PACKAGE DIMENSIONS

### **SMB** CASE 403A-03 ISSUE G





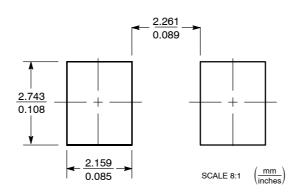


#### NOTES

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- CONTROLLING DIMENSION: INCH.
   D DIMENSION SHALL BE MEASURED WITHIN DIMENSION P.

	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	1.90	2.13	2.45	0.075	0.084	0.096
A1	0.05	0.10	0.20	0.002	0.004	0.008
b	1.96	2.03	2.20	0.077	0.080	0.087
С	0.15	0.23	0.31	0.006	0.009	0.012
D	3.30	3.56	3.95	0.130	0.140	0.156
E	4.06	4.32	4.60	0.160	0.170	0.181
HE	5.21	5.44	5.60	0.205	0.214	0.220
L	0.76	1.02	1.60	0.030	0.040	0.063
L1		0.51 REF			0.020 REF	

## **SOLDERING FOOTPRINT\***



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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